Yunpeng Wang

List of Publications by Year
in descending order

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60 papers	446 citations	759233 12 h-index	888059 17 g-index
60 all docs	60 docs citations	60 times ranked	221 citing authors

#	Article	IF	Citations
1	Morphology evolution of the anodized tin oxide film during early formation stages at relatively high constant potential. Surface and Coatings Technology, 2020, 388, 125592.	4.8	38
2	Synthesis of Cu@Ag coreâ€“shell nanoparticles for characterization of thermal stability and electric resistivity. Applied Physics A: Materials Science and Processing, 2018, 124, 1.	2.3	25
3	Fabrication of cerium myristate coating for a mechanochemically robust modifier-free superwettability system to enhance the corrosion resistance on 316L steel by one-step electrodeposition. Surface and Coatings Technology, 2020, 398, 125970.	4.8	23
4	Recycling Si waste cut from diamond wire into high performance porous Si@SiO2@C anodes for Li-ion battery. Journal of Hazardous Materials, 2021, 407, 124778.	12.4	22
5	In situ study on Cuâ€“Ni cross-interaction in Cu/Sn/Ni solder joints under temperature gradient. Journal of Materials Research, 2016, 31, 609-617.	2.6	20
6	Size effect on IMC growth induced by Cu concentration gradient and pinning of Ag 3 Sn particles during multiple reflows. Intermetallics, 2017, 90, 90-96.	3.9	18
7	Roles of interfacial heat transfer and relative solder height on segregated growth behavior of intermetallic compounds in Sn/Cu joints during furnace cooling. Intermetallics, 2018, 93, 186-196.	3.9	17
8	Morphology-controlled synthesis of Co9S8 nanotubes for ethanol gas sensors. Applied Surface Science, 2022, 585, 152764.	6.1	15
9	Synchrotron radiation imaging study on the rapid IMC growth of Snâ€“xAg solders with Cu and Ni substrates during the heat preservation stage. Journal of Materials Science: Materials in Electronics, 2018, 29, 589-601.	2.2	14
10	Effect of cooling condition and Ag on the growth of intermetallic compounds in Sn-based solder joints. Applied Physics A: Materials Science and Processing, 2016, 122, 1.	2.3	13
11	Size effect on interface reaction of Snâ€“xCu/Cu solder joints during multiple reflows. Journal of Materials Science: Materials in Electronics, 2019, 30, 4359-4369.	2.2	13
12	Formation mechanism and kinetic analysis of the morphology of Cu6Sn5 in the spherical solder joints at the Sn/Cu liquidâ€“solid interface during soldering cooling stage. Journal of Materials Science: Materials in Electronics, 2017, 28, 5398-5406.	2.2	12
13	Effect of initial Cu concentration on the IMC size and grain aspect ratio in Snâ€“xCu solders during multiple reflows. Journal of Materials Science: Materials in Electronics, 2018, 29, 602-613.	2.2	12
14	Insight into the interatomic competitive mechanism for interfacial stability of room temperature liquid GaInSn/Cu electrode. Materials Chemistry and Physics, 2021, 270, 124809.	4.0	12
15	Ultrasound assisted large scale fabrication of superhydrophilic anodized SnOx films with highly uniformed nanoporous arrays. Materials Chemistry and Physics, 2020, 242, 122540.	4.0	11
16	PTFE/EP Reinforced MOF/SiO₂ Composite as a Superior Mechanically Robust Superhydrophobic Agent towards Corrosion Protection, Selfâ€Cleaning and Antiâ€Icing. Chemistry - A European Journal, 2022, 28, e202103220.	3.3	11
17	Effect of the $$ext {TiO}_2$$ TiO 2 Nanoparticles on the Growth Behavior of Intermetallics in Sn/Cu Solder Joints. Metals and Materials International, 2019, 25, 499-507.	3.4	10
18	Effect of Cu Preferential Orientation on the Microstructure and Properties of Anodized Cu<i>_x</i>O Films. European Journal of Inorganic Chemistry, 2020, 2020, 261-268.	2.0	10

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19	Facile synthesis of W18O49/Graphene nanocomposites for highly sensitive ethanol gas sensors. Colloids and Surfaces A: Physicochemical and Engineering Aspects, 2021, 616, 126300.	4.7	10
20	Geometrical Effects of Cu@Ag Coreâ€“Shell Nanoparticles Treated Flux on the Growth Behaviour of Intermetallics in Sn/Cu Solder Joints. Electronic Materials Letters, 2019, 15, 253-265.	2.2	9
21	Controllable synthesis of porous Co3O4 nanorods and their ethanol-sensing performance. Ceramics International, 2022, 48, 29659-29668.	4.8	9
22	Superhydrophobic Surface and Lubricantâ€•Infused Surface: Implementing Two Extremes on Electrodeposited Niï£¿TiO₂ Surface to Drive Optimal Wettability Regimes for Dropletsâ€™ Multifunctional Behaviors. Advanced Engineering Materials, 2021, 23, 2100266.	3.5	8
23	Geometrical outline evolution and size-inhibiting interaction of interfacial solder bubbles and IMCs during multiple reflows. Vacuum, 2017, 145, 103-111.	3.5	7
24	Pronounced electromigration of GaInSn/Cu interconnects under super low critical current density. Materials Letters, 2021, 300, 130137.	2.6	7
25	Formation of Nanoporous Anodized Tin Oxide Films in Electrolyte Containing Fâˆ’ and S2âˆ’. ECS Journal of Solid State Science and Technology, 2020, 9, 104010.	1.8	7
26	Electrodeposited Ni-W coatings as the effective reaction barrier at Ga-21.5In-10Sn/Cu interfaces. Surfaces and Interfaces, 2022, 30, 101838.	3.0	7
27	Shielding effect of Ag3Sn on growth of intermetallic compounds in isothermal heating and cooling during multiple reflows. Journal of Materials Science: Materials in Electronics, 2018, 29, 4383-4390.	2.2	6
28	Significant effect of orientation on Cu6Sn5 coarsening behavior in isothermal aging process. Journal of Materials Science: Materials in Electronics, 2020, 31, 21335-21341.	2.2	6
29	Microstructure heritance of metallographic feature in the anodization of carbon steels. Materials Letters, 2021, 288, 129410.	2.6	6
30	Designing micro-nano structure of anodized iron oxide films by metallographic adjustment on T8 steel. Ceramics International, 2021, 47, 32954-32962.	4.8	6
31	Study on the Crystallinity and Oxidation States of Nanoporous Anodized Tin Oxide Films Regulated by Annealing Treatment for Supercapacitor Application. Langmuir, 2022, 38, 164-173.	3.5	6
32	Effect of polycrystalline Cu microstructures on IMC growth behavior at Sn/Cu soldering interface. Journal of Materials Science: Materials in Electronics, 2019, 30, 15964-15971.	2.2	5
33	Growth behavior of preferentially scalloped intermetallic compounds at extremely thin peripheral Sn/Cu interface. Journal of Materials Science: Materials in Electronics, 2019, 30, 2872-2887.	2.2	5
34	Modelling the melting of Sn0.7Cu solder using the enthalpy method. , 2016, , .		4
35	Positive feedback on imposed thermal gradient by interfacial bubbles in Cu/liquid Sn-3.5Ag/Cu joints. , 2016, , .		4
36	Effect of Zn content on interfacial reactions of Ni/Snâ€“xZn/Ni joints under temperature gradient. Journal of Materials Research, 2017, 32, 3555-3563.	2.6	4

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37	Low temperature engineering feasibility of high reflective Agâ€“Sn films from experimental and thermodynamic views. Materials Chemistry and Physics, 2020, 254, 123490.	4.0	4
38	Effect of substrate surface roughness on interfacial reaction at Sn-3.0Ag/(001)Cu interface. Vacuum, 2022, 197, 110816.	3.5	4
39	A facile strategy to <i>in situ</i> synthesize metal oxide/conductive polymer hybrid electrodes for supercapacitors. Soft Matter, 2022, 18, 2517-2521.	2.7	4
40	All-round suppression of Cu6Sn5 growth in Sn/Cu joints by utilizing TiO2 nanoparticles. Journal of Materials Science: Materials in Electronics, 2018, 29, 15966-15972.	2.2	3
41	Effects of TiO2 nanoparticles addition on physical and soldering properties of Snâ€“xTiO2 composite solder. Journal of Materials Science: Materials in Electronics, 2019, 30, 18828-18837.	2.2	3
42	Synthesizing robust cuprous oxide film with adjustable morphologies as surface-enhanced Raman scattering substrate by copper anodization. Materials Chemistry and Physics, 2021, 264, 124470.	4.0	3
43	Competitive growth of Cu3Sn and Cu6Sn5 at Sn/Cu interface during various multi-reflow processes. Journal of Materials Science: Materials in Electronics, 2021, 32, 22771-22779.	2.2	3
44	Insight into the effect of reorganized chemical short-range orders at Ga-based alloys/Cu interfaces on the nucleation and growth of CuGa2 crystals. Materials Letters, 2022, 307, 131029.	2.6	3
45	Interfacial reactions at Ga-21.5Inâ€“10Sn/Cu liquid-solid interfaces under isothermal and non-isothermal conditions. Materials Chemistry and Physics, 2022, 282, 125960.	4.0	3
46	Quantitative polynomial free energy based phase field model for void motion and evolution in Sn under thermal gradient. , 2017, , .		1
47	Formation of preferred orientation of Cu<inf>6</inf>Sn<inf>5</inf> grains in Cu/Sn/Cu interconnects by soldering under temperature gradient. , 2017, , .		1
48	Growth Behavior of Cu<inf>6</inf>Sn<inf>5</inf> Grains at Sn/(001)Cu Interface by Imposing Temperature Gradient. , 2018, , .		1
49	Simulation for Cu Atom Diffusion Leading to Fluctuations in Solder Properties and Cu6Sn5 Growth during Multiple Reflows. Metals, 2021, 11, 2041.	2.3	1
50	Effect of Ag concentration on the Cu<inf>6</inf>Sn<inf>5</inf> growth in Sn-based solder/Cu joints at the isothermal reflow stage. , 2017, , .		0
51	In situ study the effects of Cu addition on the rapidly growth of Cu<inf>6</inf>Sn<inf>5</inf> at the Sn-base solder/Cu L-S interface during soldering heat preservation stage. , 2017, , .		0
52	A Computational Model for Simulation of Temperature During Radio-Frequency Ablation of Biological Tissue. , 2018, , .		0
53	Stability of Multilayered Ag/Ag<inf>3</inf>Sn/Sn Films Noncyanide Electroplateded for high-reflective back-electrode. , 2018, , .		0
54	Effect of Temperature Gradient on Interfacial Reactions in Cu/Sn-9Zn/Ni Solder Joints during Aging. , 2018, , .		0

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55	Influence of Cu nanoparticles on Cu<inf>6</inf>Sn<inf>5</inf> growth behavior at the interface of Sn/Cu solder joints. , 2018, , .		0
56	Effect of Ag content on Cu<inf>6</inf>Sn<inf>5</inf> growth behavior at Sn-Ag/Cu solder interface during multiple reflows. , 2018, , .		0
57	The study of edge effects in Sn-0.5Cu/(001)Cu during soldering cooling stage. , 2020, , .		0
58	Study on the coordination agent system of Sn-Ag-Cu ternary alloy co-deposition. , 2020, , .		0
59	Influence of Sn crystal preferred orientation on the reflective and environmental stability of electroplated Sn/Ag films. Materials Chemistry and Physics, 2021, 265, 124522.	4.0	0
60	Growth mechanism and kinetics of Cu3Sn in the interfacial reaction between liquid Sn and diversely oriented Cu substrates. Journal of Materials Science: Materials in Electronics, 2022, 33, 2957-2969.	2.2	0